

# MATERIAL DECLARATION SHEET



Material Number	CAY10-J2 Series			
Product Line	Thick Film Chip Resistors Arrays			
Compliance Date	4-1-2003 DC0314			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00081889714	Aluminum oxide	1344-28-1	96%	0.00078614125	76.05%
				Crystalline Silica Quartz	14808-60-7	4%	0.00003275589	3.17%
2	Conductor Layer	Conductor Ink	0.00003907386	Silver	7440-22-4	96%	0.00003751090560	3.63%
				Bismuth	7440-69-9	1%	0.00000039073860	0.04%
				Barium	7440-39-3	1%	0.00000039073860	0.04%
				Silicon	7440-21-3	1%	0.00000039073860	0.04%
				Boron	7440-42-8	1%	0.00000039073860	0.04%
3	Resistive Element	Resistive Ink	0.00002594587	Ruthenium oxide	12036-10-1	25%	0.00000648646750	0.63%
				Silver	7440-22-4	40%	0.00001037834800	1.00%
				Palladium	7440-05-3	15%	0.00000389188050	0.38%
				Lead	7439-92-1	20%	0.00000518917400	0.50%
4	Over Coating	Epoxy	0.00002470543	Epoxy	29690-82-2	100%	0.000024705430	2.39%
5	End Terminal	NI-CR	0.00003700646	Nickel	7440-02-0	80%	0.00002960516800	2.86%
				Chromium	7440-47-3	20%	0.00000740129200	0.72%
6	Nickel Plating	Nickel	0.00004837716	Nickel	7440-02-0	100%	0.0000483772	4.68%
7	Tin Plating	Tin	0.00003969408	Tin	7440-31-5	100%	0.0000396941	3.84%
			Total weight	0.0010337				

**This Document was updated on: 4-11-2016**

**Important remarks:** Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I